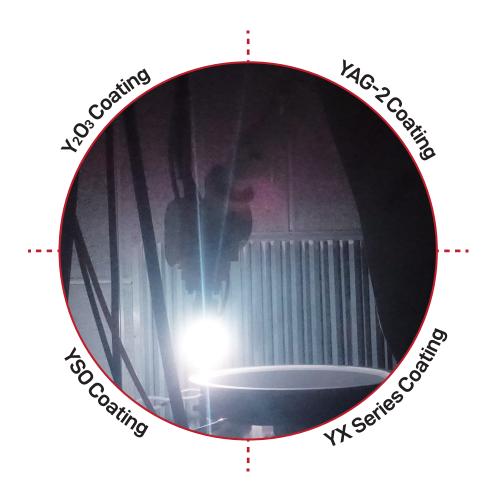
14nm Etch Coating

# APS











### **About**

Atmospheric plasma spraying ionizes incombustible gases such as argon, hydrogen, nitrogen, or helium in a special chamber to form the plasma composed of electrons, neutrons, and protons. With the high temperature and high-speed plasma blown out of the chamber, a high-density coating film is formed by transferring the powder material in the flame at a uniform speed and melting and spraying power material on the substrate material.

CINOS APS Coating can provide various coatings such as Y<sub>2</sub>O<sub>3</sub>, YX, YX-<sub>2</sub> YAG-<sub>2</sub>, YSO, and provide a coating suitable for the characteristics of the semiconductor parts.



APS  $Y_2O_3$  coating is the most widely used corrosion-resistant coating which has a lower etching rate in a plasma environment compared to the substrate material of major semiconductor facilities such as Al and Al $_2O_3$  and it can be applied to various facilities.

In the case of the APS YX Series, the YF3 and YOF coatings are applied to the etch chambers for the minimization of the by-products in semiconductor etching facilities. Especially, in the case of YX-2 (YOF) coating, the deposition formed after use in the chamber and the coating have similar components, so the generation of by-products is small.





YAG (Yttrium Aluminum Garnet) has a complex garnet structure with YO $_3$ , AlO $_4$ , and AlO $_4$ , so its hardness is higher than that of Y $_2$ O $_3$  and YX and, therefore, has a low etching rate in a plasma environment. CINOS YAG-2 Coating crystallographically has the YAM (Yttrium Aluminum Monoclinic) structure, which is a deformation phase of YAG, and the hardness of the

coating is similar to YAG. In the case of the pre-existing YAG, a bond coating was required due to the low bonding strength, but for YAG-2 coating, the single-layer coating is possible.

APS YSO coating has a **Si-O structure** in its structure, so its hardness characteristics are the best among APS coatings. In addition, it has characteristics such as heat resistance, thermal integrity resistance, and low thermal expansion properties, so it is used as a thermal barrier coating. So it has characteristics suitable for high-temperature process facilities.

YX-1



**YSO** 

# **Application**

By coating major parts such as liners, doors, and shields of **sub 14nm semi-conductor etch facilities**, the lifetime of parts can be increased and byproducts from the coating are minimized during the process to improve yield.



### Hardness 512 368 587 899 900 (H<sub>V</sub>) Adhesion 5 5 5 9 6 (MPa) Roughness 200±50 300±50 200±50 200±50 200±50 (µinch) Porosity 3~5↓ 3~5↓ 3~5↓ 2 2 (%)

YX-2

YAG-2

## Mechanism

Y2O3











**Best Solution** 



For Sub 14nm Etch Equipment

